

BTA316 series B and C

16 A Three-quadrant triacs high commutation

Rev. 01 — 11 April 2007

Product data sheet

1. Product profile

1.1 General description

Passivated, new generation, high commutation triacs in a SOT78 plastic package

1.2 Features

- Very high commutation performance maximized at each gate sensitivity
- High immunity to dV/dt

1.3 Applications

- High power motor control - e.g. washing machines and vacuum cleaners
- Refrigeration and air conditioning compressors
- Non-linear rectifier-fed motor loads
- Electronic thermostats

1.4 Quick reference data

- $V_{DRM} \leq 600$ V (BTA316-600B/C)
- $V_{DRM} \leq 800$ V (BTA316-800B/C)
- $I_{TSM} \leq 140$ A ($t = 20$ ms)
- $I_{GT} \leq 50$ mA (BTA316 series B)
- $I_{GT} \leq 35$ mA (BTA316 series C)
- $I_{T(RMS)} \leq 16$ A

2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Symbol
1	main terminal 1 (T1)		 sym051
2	main terminal 2 (T2)		
3	gate (G)		
mb	mounting base; main terminal 2 (T2)		

SOT78 (TO-220AB)

3. Ordering information

Table 2. Ordering information

Type number	Package		Version
	Name	Description	
BTA316-600B	SC-46	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78
BTA316-600C			
BTA316-800B			
BTA316-800C			

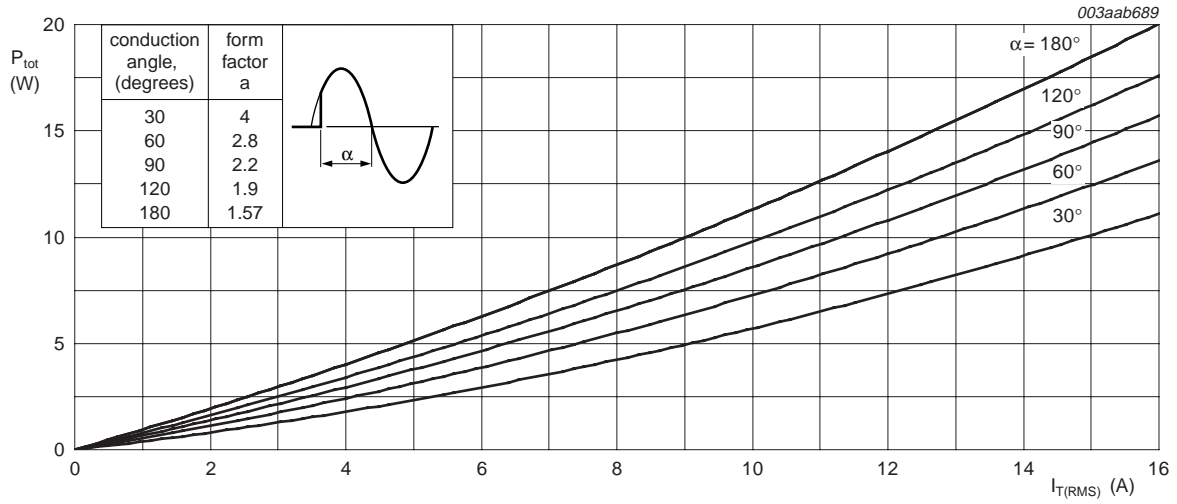
4. Limiting values

Table 3. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

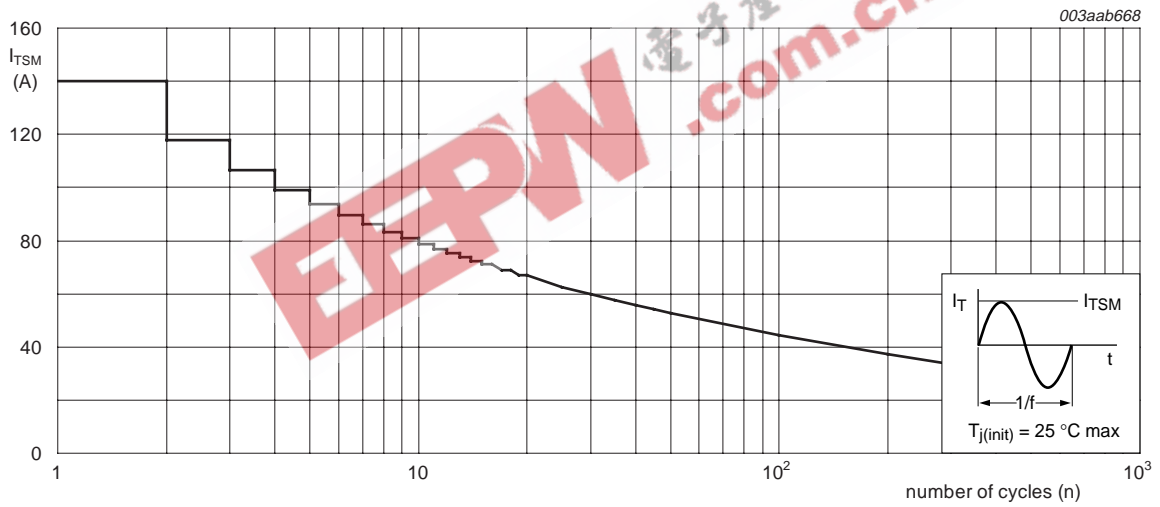
Symbol	Parameter	Conditions	Min	Max	Unit
V _{DRM}	repetitive peak off-state voltage	BTA316-600B; BTA316-600C ^[1]	-	600	V
		BTA316-800B; BTA316-800C	-	800	V
I _{T(RMS)}	RMS on-state current	full sine wave; T _{mb} ≤ 101 °C; see Figure 4 and 5	-	16	A
I _{TSM}	non-repetitive peak on-state current	full sine wave; T _j = 25 °C prior to surge; see Figure 2 and 3	-	-	-
		t = 20 ms	-	140	A
		t = 16.7 ms	-	150	A
I ² t	I ² t for fusing	t = 10 ms	-	98	A ² s
di _T /dt	rate of rise of on-state current	I _{TM} = 20 A; I _G = 0.2 A; di _G /dt = 0.2 A/μs	-	100	A/μs
I _{GM}	peak gate current		-	2	A
P _{GM}	peak gate power		-	5	W
P _{G(AV)}	average gate power	over any 20 ms period	-	0.5	W
T _{stg}	storage temperature		-40	+150	°C
T _j	junction temperature		-	125	°C

[1] Although not recommended, off-state voltages up to 800 V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 15 A/μs.



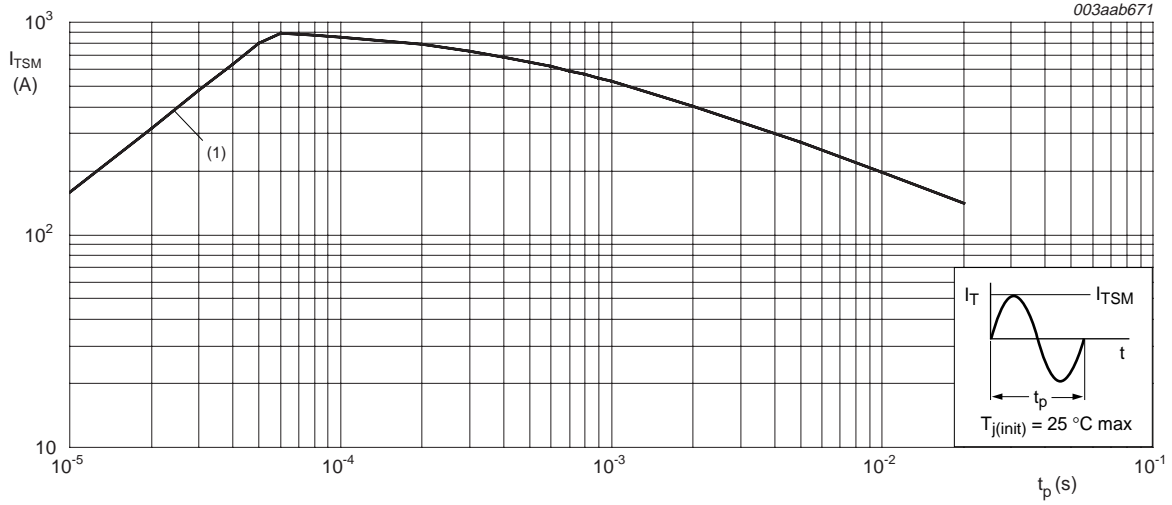
α = conduction angle

Fig 1. Total power dissipation as a function of RMS on-state current; maximum values



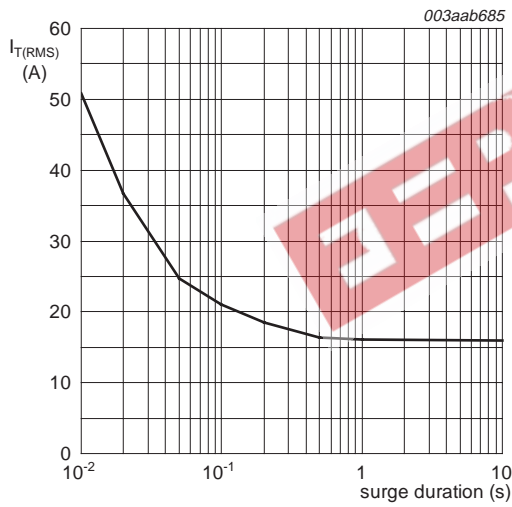
f = 50 Hz

Fig 2. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



$t_p \leq 20 \text{ ms}$
 (1) di_T/dt limit

Fig 3. Non-repetitive peak on-state current as a function of pulse duration; maximum values



$f = 50 \text{ Hz}$;
 $T_{mb} = 101 \text{ °C}$

Fig 4. RMS on-state current as a function of surge duration; maximum values

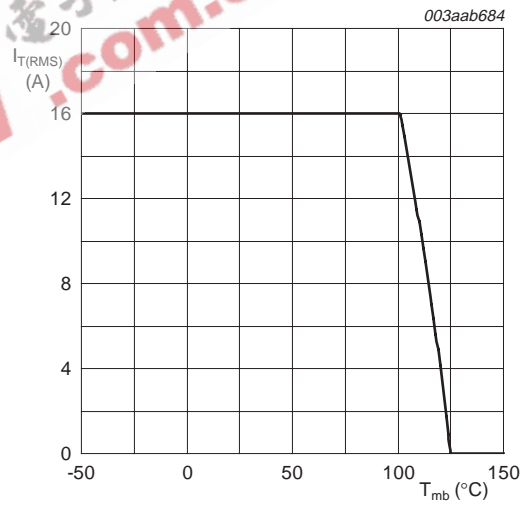
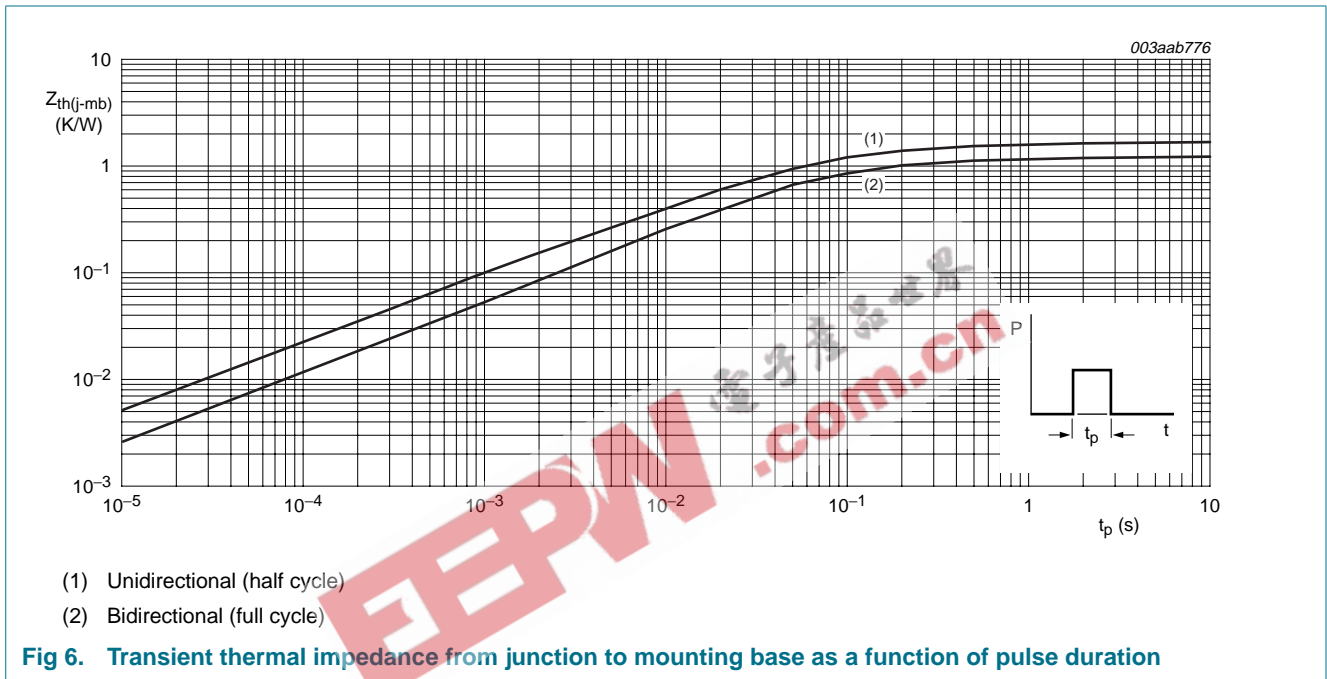


Fig 5. RMS on-state current as a function of mounting base temperature; maximum values

5. Thermal characteristics

Table 4. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	half cycle; see Figure 6	-	-	1.7	K/W
		full cycle; see Figure 6	-	-	1.2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	-	60	-	K/W



6. Static characteristics

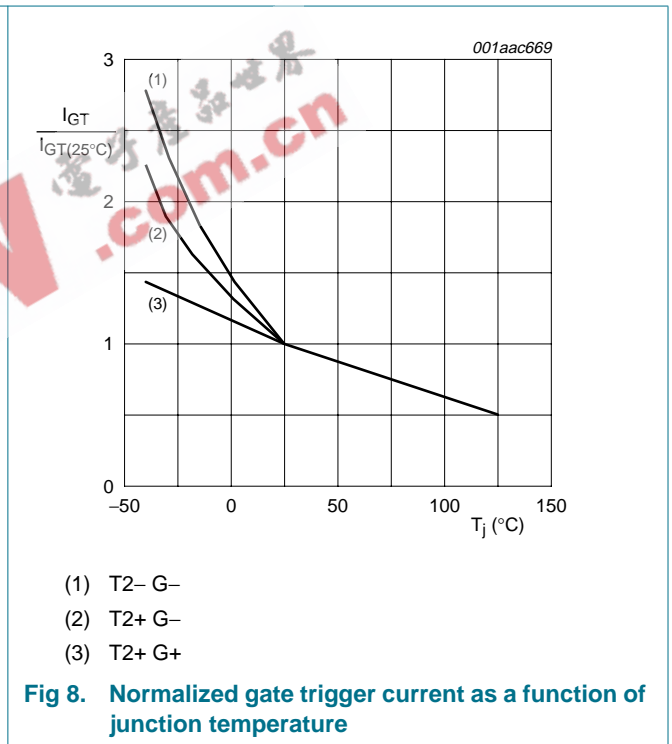
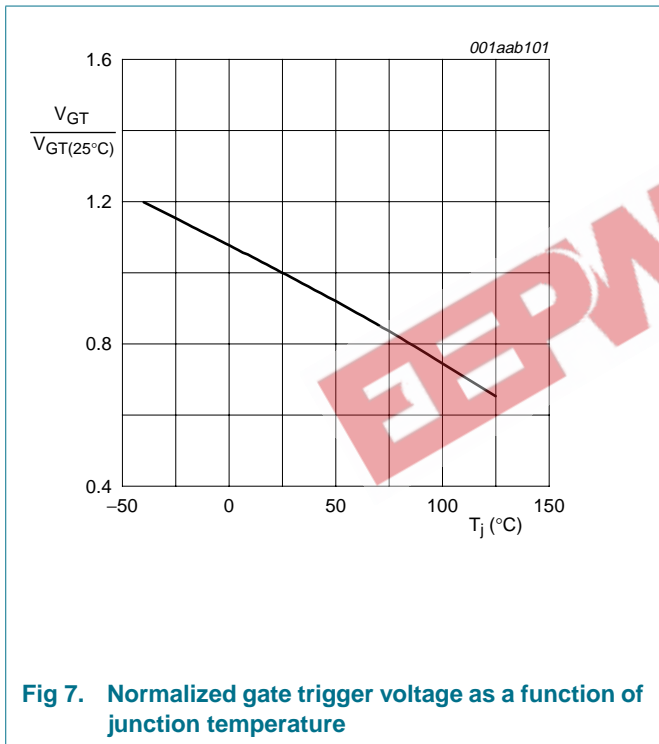
Table 5. Static characteristics
T_j = 25 °C unless otherwise specified.

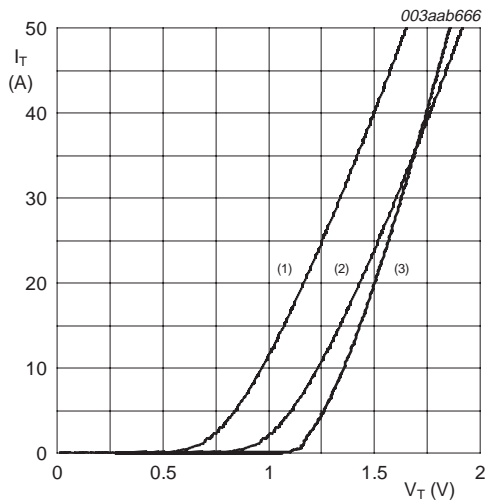
Symbol	Parameter	Conditions	BTA316-600B BTA316-800B			BTA316-600C BTA316-800C			Unit
			Min	Typ	Max	Min	Typ	Max	
I _{GT}	gate trigger current	V _D = 12 V; I _T = 0.1 A; see Figure 8							
		T2+ G+	2	-	50	2	-	35	mA
		T2+ G-	2	-	50	2	-	35	mA
I _L	latching current	V _D = 12 V; I _{GT} = 0.1 A; see Figure 10							
		T2+ G+	-	-	60	-	-	50	mA
		T2+ G-	-	-	90	-	-	60	mA
I _H	holding current	V _D = 12 V; I _{GT} = 0.1 A; see Figure 11	-	-	60	-	-	35	mA
		T2- G-	-	-	60	-	-	50	mA
		T2- G-	-	-	60	-	-	50	mA
V _T	on-state voltage	I _T = 18 A; see Figure 9	-	1.3	1.5	-	1.3	1.5	V
V _{GT}	gate trigger voltage	V _D = 12 V; I _T = 0.1 A; see Figure 7	-	0.8	1.5	-	0.8	1.5	V
		V _D = 400 V; I _T = 0.1 A; T _j = 125 °C	0.25	0.4	-	0.25	0.4	-	V
I _D	off-state current	V _D = V _{DRM(max)} ; T _j = 125 °C	-	0.1	0.5	-	0.1	0.5	mA

7. Dynamic characteristics

Table 6. Dynamic characteristics

Symbol	Parameter	Conditions	BTA316-600B BTA316-800B			BTA316-600C BTA316-800C			Unit
			Min	Typ	Max	Min	Typ	Max	
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 0.67 \times V_{DRM(max)}$; $T_j = 125\text{ }^\circ\text{C}$; exponential waveform; gate open circuit	1000	-	-	500	-	-	V/ μs
di_{com}/dt	rate of change of commutating current	$V_{DM} = 400\text{ V}$; $T_j = 125\text{ }^\circ\text{C}$; $I_{T(RMS)} = 16\text{ A}$; without snubber; gate open circuit	20	-	-	15	-	-	A/ms
t_{gt}	gate-controlled turn-on time	$I_{TM} = 20\text{ A}$; $V_D = V_{DRM(max)}$; $I_G = 0.1\text{ A}$; $di_G/dt = 5\text{ A}/\mu\text{s}$	-	2	-	-	2	-	μs





$V_o = 1.024 \text{ V}$

$R_s = 0.021 \text{ } \Omega$

- (1) $T_j = 125 \text{ } ^\circ\text{C}$; typical values
- (2) $T_j = 125 \text{ } ^\circ\text{C}$; maximum values
- (3) $T_j = 25 \text{ } ^\circ\text{C}$; maximum values

Fig 9. On-state current as a function of on-state voltage

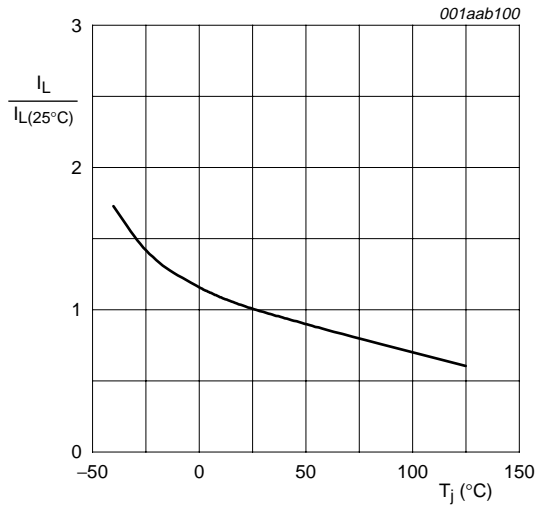


Fig 10. Normalized latching current as a function of junction temperature

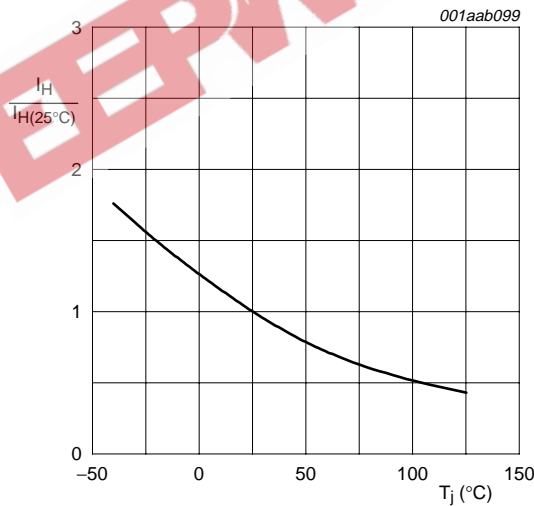


Fig 11. Normalized holding current as a function of junction temperature

8. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78

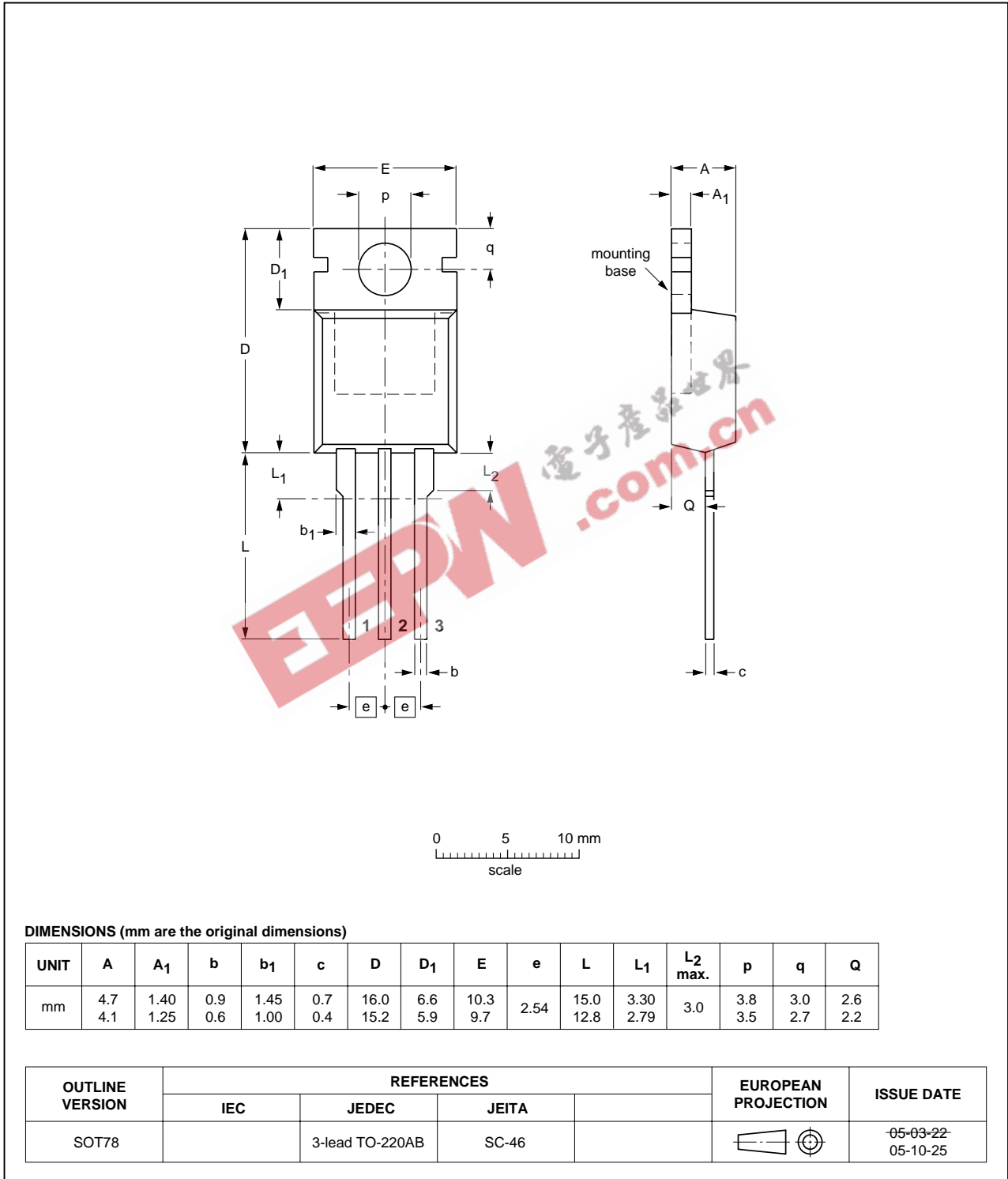


Fig 12. Package outline SOT78 (3-lead TO-220AB)

9. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BTA316_SER_B_C_1	20070411	Product data sheet	-	-

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10.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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